## SN54LS540, SN54LS541, SN74LS540, SN74LS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SDLS180 - AUGUST 1979 - REVISED MARCH 1988

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- P-N-P Inputs Reduce D-C Loading
- Hysteresis at Inputs Improves Noise Margins
- Data Flow-thru Pinout (All Inputs on Opposite Side from Outputs)

#### description

These octal buffers and line drivers are designed to have the performance of the popular SN54LS240/SN74LS240 series and, at the same time, offer a pinout having the inputs and outputs on opposite sides of the package. This arrangement greatly enhances printed circuit board layout.

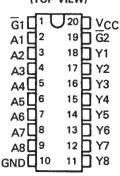
The three-state control gate is a 2-input NOR such that if either  $\overline{G1}$  or  $\overline{G2}$  are high, all eight outputs are in the high-impedance state.

The 'LS540 offers inverting data and the 'LS541 offers true data at the outputs.

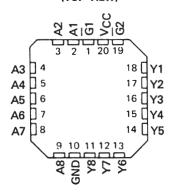
The SN54LS540 and SN54LS541 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74LS540 and SN74LS541 are characterized for operation from 0°C to 70°C.

TYPE	RATED	RATED	TYPICAL	POWER				
	IOL	¹он	DISSIPATION					
	(SINK	(SOURCE	(ENAB	LED)				
	CURRENT)	CURRENT)	'LS540	'L\$541				
SN54LS'	12 mA	- 12 mA	92.5 mW	120 mW				
SN74LS'	24 mA	- 15 mA	92.5 mW	120 mW				

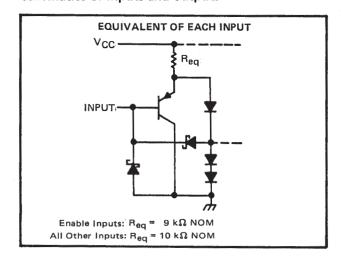
SN54LS540, SN54LS541 . . . J OR W PACKAGE SN74LS540, SN74LS541 . . . DW OR N PACKAGE (TOP VIEW)

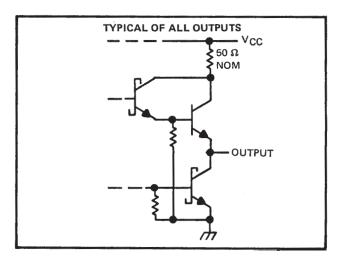


## SN54LS540, SN54LS541 . . . FK PACKAGE (TOP VIEW)



#### schematics of inputs and outputs





PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

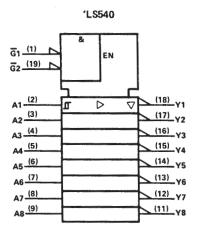


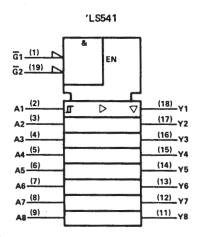
Copyright © 1988, Texas Instruments Incorporated

## SN54LS540, SN54LS541, SN74LS540, SN74LS541 **OCTAL BUFFERS AND LINE DRIVERS** WITH 3-STATE OUTPUTS

SDLS180 - AUGUST 1979 - REVISED MARCH 1988

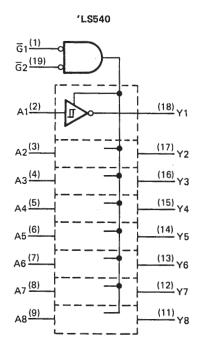
#### logic symbols†

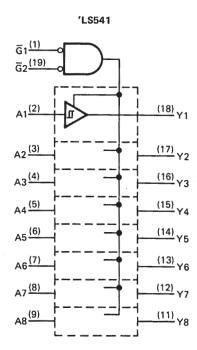




<sup>&</sup>lt;sup>†</sup> These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram (positive logic)





#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		 7 V
Input voltage		
Operating free-air temperature range:	SN54LS540, SN54LS541	 $\dots$ – 55°C to 125°C
Storage temperature range		 $\dots$ – 65°C to 150°C

NOTE 1: Voltage values are with respect to the network ground terminal.



## SN54LS540, SN54LS541, SN74LS540, SN74LS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SDLS180 - AUGUST 1979 - REVISED MARCH 1988

#### recommended operating conditions

DADAMETER		SN54LS	,		UNIT		
PARAMETER	MIN	NOM	MAX	MIN	NOM	MAX	ONT
Supply voltage, V <sub>CC</sub> (see Note 1)	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-12			- 15	mA
Low-level output current, IOL			12			24	mA
Operating free-air temperature, TA	-55		125	0		70	°C

NOTE 1: Voltage values are with respect to network ground terminal.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED		TECT CON	DITIONET		SN54LS	,	SN74LS'			UNIT
	PARAMETER		TEST CON	יפאטוווט	MIN	TYP <sup>‡</sup>	MAX	MIN	TYP <sup>‡</sup>	MAX	UNII
VIH	High-level input volta	age			2			2			V
VIL	Low-level input volta	age					0.6			0.6	V
VIK	Input clamp voltage		V <sub>CC</sub> = MIN,	I <sub>I</sub> = -18 mA			-1.5			- 1.5	V
	Hysteresis (V <sub>T+</sub> -	V <sub>T</sub> _ )	V <sub>CC</sub> = MIN		0.2	0.4		0.2	0.4		V
Vou	High-level output vo	ltago		$V_{IH} = 2 V$ , $I_{OH} = -3 \text{ mA}$	2.4	3.4		2.4	3.4		V
Vон	night-level output vo	itage	$V_{CC} = MIN,$ $V_{IL} = 0.5 V,$		2			2			V
VOL	Low-level output vo	tage	$V_{CC} = MIN,$ $V_{IH} = 2 V,$	I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	V
VOL	Low-level output voi	tage	VIH = Z V, VIL = VIL max	I <sub>OL</sub> = 24 mA					0.35	0.5	<b>V</b>
lozh	Off-state output cur high-level voltage ap		V <sub>CC</sub> = MAX,	V <sub>O</sub> = 2.7 V			20			20	
lozL	Off-state output cur low-level voltage ap		V <sub>IH</sub> = 2 V, V <sub>IL</sub> = V <sub>IL</sub> max	V <sub>O</sub> = 0.4 V			- 20			- 20	μΑ
11	Input current at max input voltage	kimum	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 7 V			0.1			0.1	mA
۱н	High-level input curr	ent, any input	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V			20			20	μΑ
IIL	Low-level input curr	ent	V <sub>CC</sub> = MAX,	$V_1 = 0.4 V$			-0.2			-0.2	mA
los	Short-circuit output	current §	V <sub>CC</sub> = MAX		40		-225	-40		-225	mA
		Outnute high		'LS540		13	25		13	25	
		Outputs high	]	'LS541		18	32		18	32	
loo	Supply ourrent	Outputs low	V <sub>CC</sub> = MAX,	'LS540		24	45		24	45	<sub>mA</sub>
licc	CC Supply current Outputs lov	Outputs low	Outputs open	'LS541		30	52		30	52	] '''^
		All outputs		'LS540		30	52		30	52	
		disabled		'LS541		32	55		32	55	

<sup>&</sup>lt;sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



 $<sup>^{\</sup>ddagger}$ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C.

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

# SN54LS540, SN54LS541, SN74LS540, SN74LS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS SDLS180 - AUGUST 1979 - REVISED MARCH 1988

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25 \,^{\circ}\text{C}$

	PARAMETER	TEST CO		'LS540		'LS541			118157	
		1231 00	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
tPLH	Propagation delay time, low-to-high-level output				9	15		9	15	ns
tPHL	Propagation delay time, high-to-low-level output	C <sub>L</sub> = 45 pF, See Note 2	$R_L = 667 \Omega$ ,		9	15		10	18	ns
tPZL	Output enable time to low level				25	38		25	38	ns
tPZH	Output enable time to high level				15	25		20	32	ns
tPLZ	Output disable time from low level	C <sub>L</sub> = 5 pF,	$R_L = 667 \Omega$ ,		10	18		10	18	ns
<sup>t</sup> PHZ	Output disable time from high level	See Note 2			15	25		18	29	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.







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#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
84155012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84155012A SNJ54LS 540FK	Samples
8415501RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415501RA SNJ54LS540J	Samples
8415501RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415501RA SNJ54LS540J	Samples
8415501SA	OBSOLETE			20		TBD	Call TI	Call TI	-55 to 125		
8415501SA	OBSOLETE			20		TBD	Call TI	Call TI	-55 to 125		
84156012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
84156012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
8415601SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415601SA SNJ54LS541W	Sample
8415601SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415601SA SNJ54LS541W	Sample
JM38510/32404B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32404B2A	Sample
JM38510/32404B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32404B2A	Sample
JM38510/32404BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32404BRA	Sample
JM38510/32404BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32404BRA	Sample
JM38510/32405BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32405BRA	Sample
JM38510/32405BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32405BRA	Sample
M38510/32404B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32404B2A	Sample
M38510/32404B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32404B2A	Sample
M38510/32404BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32404BRA	Sample





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Orderable Device	Status	Package Type		Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	<b>Device Marking</b>	Sample
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
M38510/32404BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32404BRA	Sample
M38510/32405BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32405BRA	Sample
M38510/32405BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32405BRA	Sample
SN54LS540J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS540J	Sampl
SN54LS540J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS540J	Sampl
SN54LS541J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS541J	Sampl
SN54LS541J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS541J	Sampl
SN74LS540DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Sampl
SN74LS540DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Samp
SN74LS540DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Samp
SN74LS540DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Samp
SN74LS540DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Samp
SN74LS540DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Samp
SN74LS540DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Samp
SN74LS540DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Samp
SN74LS540N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS540N	Samp
SN74LS540N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS540N	Samp
SN74LS540N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74LS540N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		





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Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74LS540NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS540N	Sample
SN74LS540NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS540N	Sample
SN74LS540NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS540	Sample
SN74LS540NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS540	Sample
SN74LS541DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Sample
SN74LS541DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Sample
SN74LS541DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Sample
SN74LS541DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Sample
SN74LS541DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Sample
SN74LS541DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Sample
SN74LS541DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Sample
SN74LS541DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Sample
SN74LS541N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS541N	Sample
SN74LS541N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS541N	Sample
SN74LS541N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74LS541N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74LS541NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS541N	Sample
SN74LS541NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS541N	Sample
SN74LS541NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS541	Sample



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS541NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	(3) Level-1-260C-UNLIM	0 to 70	74LS541	Sample
SN74LS541NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS541	Sample
SN74LS541NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS541	Sample
SNJ54LS540FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84155012A SNJ54LS 540FK	Sample
SNJ54LS540FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84155012A SNJ54LS 540FK	Sample
SNJ54LS540J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415501RA SNJ54LS540J	Sample
SNJ54LS540J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415501RA SNJ54LS540J	Sampl
SNJ54LS540W	OBSOLETE			20		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS540W	OBSOLETE			20		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS541FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS541FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS541J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS541J	Sampl
SNJ54LS541J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS541J	Sampl
SNJ54LS541W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415601SA SNJ54LS541W	Sampl
SNJ54LS541W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415601SA SNJ54LS541W	Sampl

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

#### PACKAGE OPTION ADDENDUM



17-Dec-2015

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54LS540, SN54LS541, SN74LS540, SN74LS541:

Catalog: SN74LS540, SN74LS541

Military: SN54LS540, SN54LS541

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

## PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
ľ	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS540DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LS540DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS540NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1
SN74LS541DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS541NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1

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\*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS540DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74LS540DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS540NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74LS541DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS541NSR	SO	NS	20	2000	367.0	367.0	45.0

#### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## W (R-GDFP-F20)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

  D. Index point is provided on cap for terminal identification only.

  E. Falls within Mil—Std 1835 GDFP2—F20



## FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

## PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



## DW (R-PDSO-G20)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



## DW (R-PDSO-G20)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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